

# **Japan TC Chapter 3D Packaging & Integration (3DP&I) Global Technical Committee**

**Liaison Report | June 2021**

**V1.1**

# Meeting Information

- Last meeting
  - Friday, May 28, 2021 at the SEMI Standards Japan Spring Meetings
    - Web Conference
- Next meeting
  - Friday, October 22, 2021
    - Web Conference

<http://www.semi.org/en/standards-events>

# Leadership Changes

- None

# Committee Structure Changes

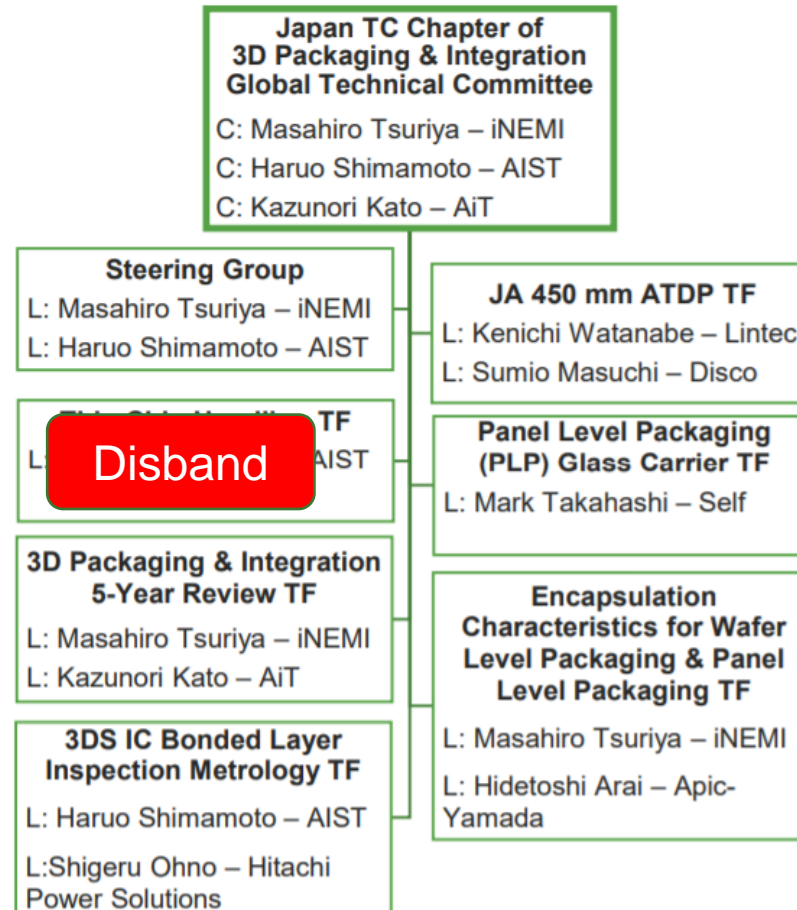
- None

# Committee Structure Changes



Previous WG/TF/SC Name	New WG/TF/SC Name or Status Change
Thin Chip Handling TF	Disband

# Organization Chart



# Ballot Results



Doc #	Document Title	TC Chapter Action
6703	Revision to SEMI G63-95 (Reapproved 0811) "Test Method for Measurement of Die Shear Strength"	<b>Failed</b> due to insufficient rate and return to TF for rework

Note 1: **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

Note 2: **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

# Activities Approved via GCS between Meetings

Doc #	Type	SC/TF/CFG	Title/Details
None			



# Authorized Activities



Doc #	Type	SC/TF/CFG	Document Title/Details
None			


**#1: SNARFs and TFOFs are available for review on the SEMI Web site at:**

**<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>**

# Other Activities Outside the Letter Ballot Process

- None

# Authorized Ballots



Doc #	When	TF	Document Title/Details
6703A	Cycle 8/9-2021	3D Packaging & Integration 5 Year Review TF	Revision to SEMI G63-95 (Reapproved 0811) "Test Method for Measurement of Die Shear Strength"

# Task Force Highlights[1/3]



- Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging TF
  - Taskforce Kick-off: November 18, 2020
  - Under development of standard document drafts for 8 encapsulate materials characteristics and 3 items for performances
  - SNARFs approval requests for 8 material characteristics
    - Ballot6706,6707,6708,6709,6710,6711,6712
  - Plan to develop final ballot draft by the end of Q3.
- Panel Level Packaging (PLP) Glass Carrier TF
  - Reviewed ballot 6590, New Standard: Specification for Glass Carrier Characteristics for Panel Level Packaging (PLP) Applications

# Task Force Highlights[2/3]



- Five Years Review TF
  - Completed the review and submitted the ballots for 2020 required review documents.
  - Will start for 2021 review needed
- 3DS IC Bonded Layer Inspection Metrology TF
  - Pre-trial using the SEMATECH sample was done by Aug. 2020.
  - Detectable void size by the nominal frequency of the transducer was defined.
  - A sample for the feasibility study was designed by Sept. 2020.
  - Manufacturing the sample for the feasibility study is delayed due to COVID and equipment trouble.

# Task Force Highlights[3/3]

- 3D Packaging & Integration Steering Group WG
  - Continue to brainstorm the potential areas of SEMI Standard.
    - Example: RDL Adhesion Strength Measurement/Metrology Proposal
  - Share the taskforce activities progress
  - Work on the joint discussion with TWN TC (held meeting on August 2020)
  - Displayed 3 posters at SEMICON Japan 2020

# Open SNARF(s)

- None

# SNARF(s) Abolished

Doc #	SC/TF/CFG	Title/Details
None		



# 5-Year Review

Designation #	Standard Title	Action By	Assigned to
None			

# Thank you!

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